

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A component lead comprising:
a lead finish comprising between about 78% and 80% by weight of lead, between about 9% and about 11% by weight of antimony, between 5% and about 12% by weight of silver about 82%–84% by weight of lead, about 2%–4% by weight of silver, about 9%–11% by weight of antimony, and a balance of tin disposed over the component lead.
2. – 3. (Canceled)
4. (Previously Presented) The lead of claim 1, wherein the component lead is to be coupled to a lead of a surface mount component.
5. (Previously Presented) The lead of claim 1, wherein the component lead is coupled to a downhole electronic assembly.
6. (Currently Amended) A package structure comprising:
a package; and
a plurality of leads coupled to a circuit included in the package and having a lead finish comprising between about 78% and 80% by weight of lead, between about 9% and about 11% by weight of antimony, between 5% and about 12% by weight of silver about 82%–84% by weight of lead, about 2%–4% by weight of silver, about 9%–11% by weight of antimony, and a balance of tin.
7. (Withdrawn) The package structure of claim 6, wherein the circuit is included in a substrate.

8. (Withdrawn) The package structure of claim 7, wherein the package structure is part of a downhole electronic assembly.

9. (Currently Amended) A circuit board, comprising:

a processor; and

a circuit coupled to the processor and included in a package structure having a plurality of leads having a lead finish comprising between about 78% and 80% by weight of lead, between about 9% and about 11% by weight of antimony, between 5% and about 12% by weight of silver about 82%–84% by weight of lead, about 2%–4% by weight of silver, about 9%–11% by weight of antimony, and a balance of tin.

10. (Withdrawn) The circuit board of claim 9, wherein the circuit includes a memory.

11. (Withdrawn) The circuit board of claim 9, wherein the circuit includes a digital-to-analog converter.

12. (Currently Amended) A system comprising:

a component lead having a lead finish disposed over the component lead, the second lead finish comprising between about 78% and 80% by weight of lead, between about 9% and about 11% by weight of antimony, between 5% and about 12% by weight of silver about 82%–84% by weight of lead, about 2%–4% by weight of silver, about 9%–11% by weight of antimony, and a balance of tin; and

a downhole transducer coupled to the component lead.

13. (Canceled)

14. (Previously Presented) The system of claim 12, wherein the downhole transducer is selected from the group consisting of a downhole temperature indicator, a downhole vibration sensor, a pressure sensor, an accelerometer, and a fluxgate.

15. (Original) The system of claim 12, wherein the downhole transducer is to measure a subsurface characteristic that is selected from a group consisting of a downhole temperature, a downhole pressure, a resistivity of a subsurface formation, a porosity of a subsurface formation, a diameter of a borehole, and a shape of the borehole.

16. (Original) The system of claim 12, further comprising:
a processor coupled to the lead.

17. (Original) The system of claim 12, further comprising:
an amplifier coupled to the lead.

18. – 39. (Canceled).

40. (Currently Amended) An assembly comprising:
a downhole transducer coupled to a circuit trace included in a circuit attached to a composition including a first amount between about 78% and 80% ~~about 82%~~ by weight of lead, a second amount between about 9% and about 11% by weight of antimony, a third amount between 5% ~~about 3%~~ and about 12% by weight of silver, and a balance of tin.

41. (Original) The assembly of claim 40, further comprising:
a processor to be communicatively coupled to the circuit.

42. (Original) The assembly of claim 40, wherein the circuit includes a data acquisition system.

43. (Original) The assembly of claim 40, wherein the circuit includes a filter.

44. – 46. (Canceled)